INTEGRATED CIRCUITS

DATA SHEET **TDA5332T** Double mixer/oscillator for TV and VCR tuners March 1989 Preliminary specification File under Integrated Circuits, IC02 WWW.DZSC.COM







TDA5332T

GENERAL DESCRIPTION

The TDA5332T is an integrated circuit that performs the mixer/oscillator functions in TV and VCR tuners. This device gives the designer the capability to design an economical and physically small tuner which will be capable of meeting the most stringent requirements e.g. FTZ or FCC. The tuner development time can be drastically reduced by using this device.

Features

- Balanced mixer with a common emitter input for band A
- Amplitude-controlled oscillator for band A
- · Balanced mixer with common base input for band B
- Balanced oscillator for band B
- SAW filter preamplifier with an output impedance of 75 Ω in application
- Bandgap voltage stabilizer for oscillator stability
- Electronic bandswitch

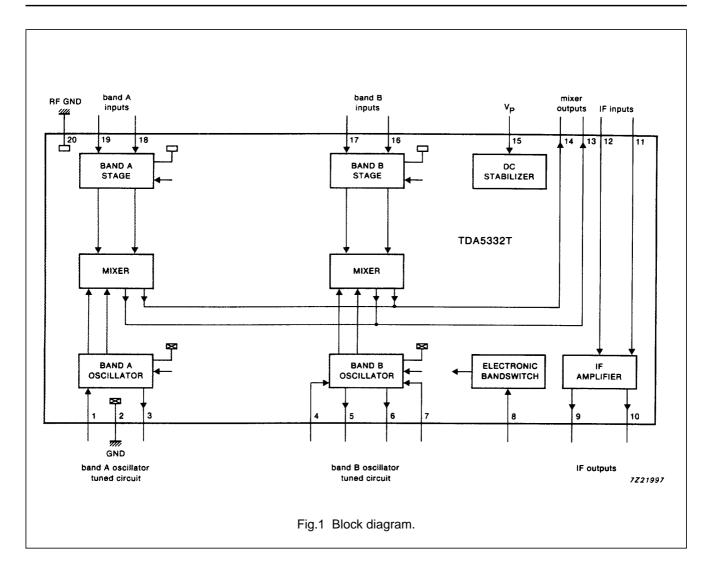
QUICK REFERENCE DATA

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage		VP	-	12	-	V
Band A frequency range	depending on application	f _A	45	-	470	MHz
Band B frequency range	depending on application	f _B	160	-	860	MHz
Band A noise factor	50 MHz	NFA	_	7.5	_	dB
Band B noise factor	860 MHz	NFB	_	9	_	dB
Band A input voltage	1% cross-modulation	V ₁₈₋₂₀	-	100	-	dBμV
Band B input power	1% cross-modulation					
	note 5	PI	_	–21	-	dBm
Band A voltage gain		G _{VA}	-	25	-	dB
Band B voltage gain		G _{VB}	-	36	_	dB

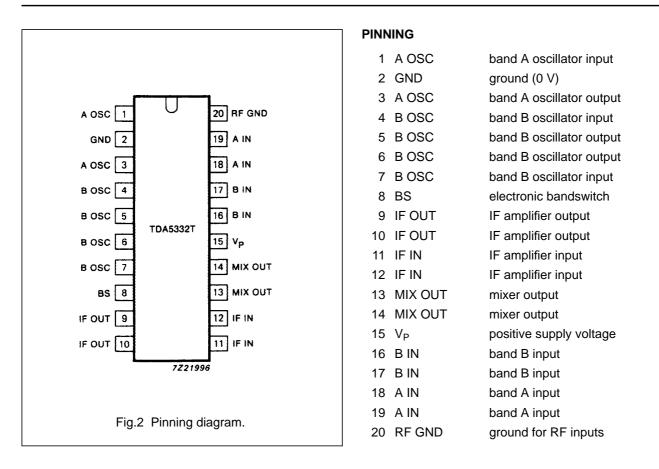
PACKAGE OUTLINE

20-lead mini-pack, plastic (SO20L; SOT163A); SOT163-1; 1996 November 29.

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RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

PARAMETER	CONDITIONS	SYMBOL	MIN.	MAX.	
Supply voltage		VP	-0.3	14	V
Switching voltage		V ₈	0	14	V
Output current of each pin to ground		Io	-	-10	mA
Maximum short-circuit time (all pins)		t _{SC}	-	10	s
Storage temperature range		T _{stg}	-55	+ 150	°C
Operating ambient temperature range		T _{amb}	-25	+ 80	°C
Junction temperature		Tj	-	+ 150	°C

THERMAL RESISTANCE

From junction to ambient in free air	R _{th j-a}	typ.	100	K/W
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HANDLING

Pins 8, 9 and 10 withstand the ESD test in accordance with MIL-STD-883C category B (2000 V).

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CHARACTERISTICS

 V_P = 12 V; T_{amb} = 25 °C; all voltages are referenced to ground (pins 2 and 20); measured in Fig.3; unless otherwise specified.

PARAMETER	CONDITIONS	SYMBOL	MIN.	T	YP.	MAX.	UNIT
Supply voltage		V ₁₅	10		_	13.2	V
Supply current		I ₁₅	_	4	12	55	mA
Switching voltage;							
band A		V _{SA}	0		_	1.1	V
band B		V _{SB}	3		_	5	V
Switching current							
band A		I _{SA}	_		_	10	μA
band B		I _{SB}	_		_	50	μA
IF Amplifier	differentially						
	measured at						
	36 MHz			mod.	phase		
Input reflection						1	
coefficient	note 4	S ₁₁	_	-0.5	-2	_	dB/º
Reverse transmission							
coefficient		S ₁₂	_	-41	-7	_	dB/º
Forward transmission							
coefficient		S ₂₁	_	12	160	_	dB/º
Output reflection							
coefficient		S ₂₂	_	-9	10	_	dB/º
Input admittance in							
application		Y	_	-	1.4	-	mS
					0.9	-	pF
Output admittance							
in application		Zo	_	_	55	_	Ω
					230	_	nH
Band A mixer	measured using				•		
(including IF amplifier)	circuit shown						
F	in Fig.3	4	45			470	
Frequency range		f _A	45	_	_ , _	470	MHz
Noise factor	50 MHz	NF	-		7.5 0	9	dB
	225 MHz	NF	-		9	11	dB
	300 MHz	NF	-		10	12	dB
	470 MHz	NF	-		11	13	dB
Optimum source							
conductance	50 MHz	G ₁₈₋₂₀	-		0.5	-	mS
	225 MHz	G ₁₈₋₂₀	-		.1	-	mS
	300 MHz	G ₁₈₋₂₀	-		.2	-	mS
	470 MHz	G ₁₈₋₂₀	-	1	.9	-	mS

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PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Input capacitance	50 – 470 MHz	C ₁₈₋₂₀	-	2.5	_	pF
Input voltage	1% cross-modulation; in channel;					
		V ₁₈₋₂₀	97	100	-	dBµV
Input voltage	10 kHz pulling; in channel; f < 300 MHz					
		V ₁₈₋₂₀	100	108	_	dBµV
Voltage gain	20 log					
	(V ₉₋₁₀ /V ₁₈)	Gv	22.5	25.0	27.5	dB
Band A mixer						
Conversion transadmittance						
mixer	$I_{13}/V_{18} = -I_{14}/V_{18}$	Ct	_	3.5	_	mS
Mixer output admittance	pins 13 and 14		_	0.1	_	mS
Mixer output capacitance		C ₁₃₋₁₄	_	2	_	pF
Band A oscillator						
Frequency range		f.	80		520	MHz
Frequency shift	ΔV _P = 10%	f _A	00	_	520	
Frequency shift	note 6; f = 330 MHz	Δf	_	_	200	kHz
Frequency drift	$\Delta T = 25 \ ^{\circ}C$					
	note 7; f = 330 MHz	Δf	-	-	400	kHz
Frequency drift	5 s to 15 min					
	after switching on;	Δf	-	_	200	kHz
	f = 330 MHz					
Band B mixer	measured using					
(including IF)	circuit shown in					
	Fig.3; measurements using hybrid; note 1					
Frequency range		f _B	160	_	860	MHz
Noise factor not corrected						
for image	pins 16 and 17					
lor mago	160 MHz	NFB	_	9	11	dB
	860 MHz	NFB		9	11	dB
Available input power	note 5; 1% cross-modulation; in channel;			Ū		
	pins 16 and 17;					
	160 MHz	P _{IB}	-25	-21	-	dBm
	860 MHz	P _{IB}	-25	-21	-	dBm
10 kHz pulling	note 5; pins 16 and 17; in channel					
	860 MHz		_	-20	_	dBm

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PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
N + 5 – 1 MHz						
pulling	notes 2 and 5; 820 MHz		-42	-35	_	dBm
Voltage gain	note 3; 160 MHz 860 MHz	G _{VB} G _{VB}	33 33	36 36	39 39	dB dB
Band B oscillator						
Frequency range		f _B	200	_	900	MHz
Frequency shift	note 6; ΔV _P = 10%	Δf	_	_	400	kHz
Frequency drift	note 7; ΔT = 25 °C	Δf	_	_	800	kHz
Frequency drift	5 s to 15 min after switching on	Δf	_	_	400	kHz

Notes to the characteristics

- 1. The values have been corrected for hybrid and cable losses. The symmetrical output impedance of the circuit is 100 Ω .
- 2. The input level of a N + 5 1 MHz signal (just visible).
- 3. The gain is defined as the transducer gain (measured in Fig.3) plus the voltage transformation ratio of L6 to L7 (6:1, 16 dB).
- 4. All S parameters are referred to a 50 Ω system.
- 5. The input power is defined as the power delivered by the generator on a 50 Ω load.
- 6. The frequency shift is defined for a variation of power supply from;
 - a) $V_P = 12 \text{ V}$ to $V_P = 10.8 \text{ V}$
 - b) $V_P = 12 \text{ V}$ to $V_P = 13.2 \text{ V}$.

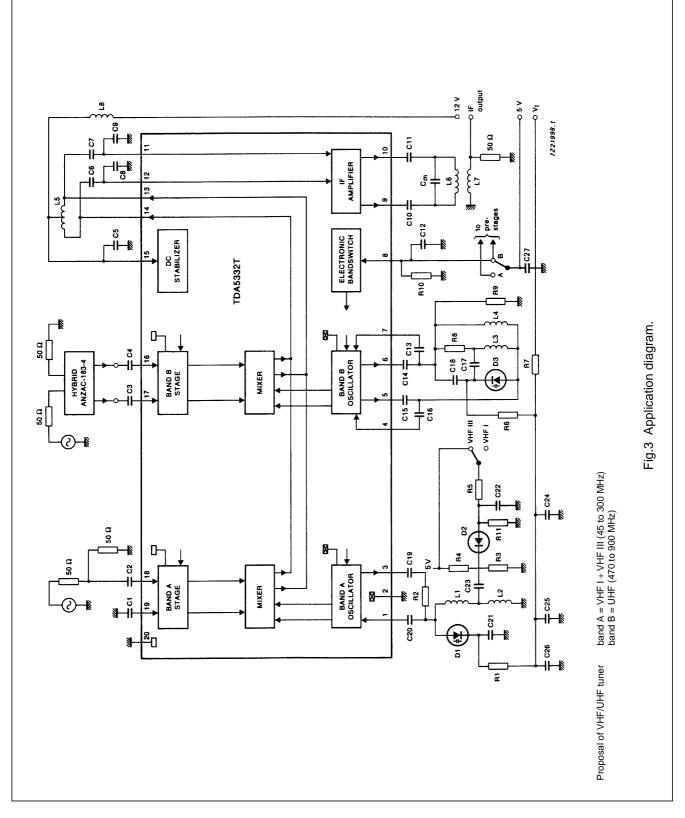
In both cases the frequency shift is below the specified value.

- 7. The frequency drift is defined for a variation of ambient temperature from;
 - a) $T_{amb} = 25 \ ^{\circ}C$ to $T_{amb} = 0 \ ^{\circ}C$
 - b) $T_{amb} = 25 \degree C$ to $T_{amb} = 50 \degree C$

In both cases the frequency shift is below the specified value.

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APPLICATION INFORMATION



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Component values of the application diagram

resistors			
R1 = 47 kΩ	R2 = 18 Ω	R3 = 1.2 kΩ	R4 = 4.7 kΩ
R5 = 100 Ω	R6 = 22 kΩ	R7 = 1 kΩ	R8 = 2.2 kΩ
R9 = 22 kΩ	R10 = 15 kΩ	R11 = 47 kΩ	
capacitors			
C1 = 1 nF	C2 = 1 nF	C3 = 1 nF	C4 = 1 nF
C5 = 1 nF	C6 = 1 nF	C7 = 1 nF	C8 = 15 pF (N750)
C9 = 15 pF (N750)	C10 = 1 nF	C11 = 1 nF	C12 = 1 nF
C13 = 0.68 pF (SMD)	C14 = 1 pF (SMD)	C15 = 1 pF (SMD)	
C16 = 0.68 pF (SMD)	C17 = 100 pF (SMD)	C18 = 5.6 pF (SMD)	C19 = 1 pF (NPO)
C20 = 1 pF (NPO)	C21 = 82 pF (N750)	C22 = 1 nF	C23 = 1 nF
C24 = 1 nF	C25 = 1 nF	C26 = 1 μF (40V)	C27 = 1 nF
Cm = 18 pF (N750)			
diodes and IC			
D1 = BB911	D2 = BA482	D3 = BB405B	IC = TDA5332T
coils			
L1 = 2.5 t (¢3)	L2 = 8.5 t (\$)	L3 = 1.5 t (¢3)	
L4 = 1.5 t (\$)	L5 = 2 × 5 t (note 1)	$L8 = 5 \ \mu H$ (choke coil)	
transformer			
L6 = 12t (note 1)	L7 = 2 t		
wire size for L1 to L4 = 0.4 a	nd for L5 to L7 = 0.1 mm.		
wire size for L1 to $L4 = 0.4$ a	nd for L5 to L7 = 0.1 mm.		

Note

1. Coil type: TOKO 7 kN; material: 113 kN, screw core (03-0093), pot core (04-0026).

OUTLINE		REFER	ENCES			
VERSION	IEC	JEDEC	EIAJ	PROJECTION		
SOT163-1	075E04	MS-013AC			-95-01-24 97-05-22	

А X = v 🕅 A HF

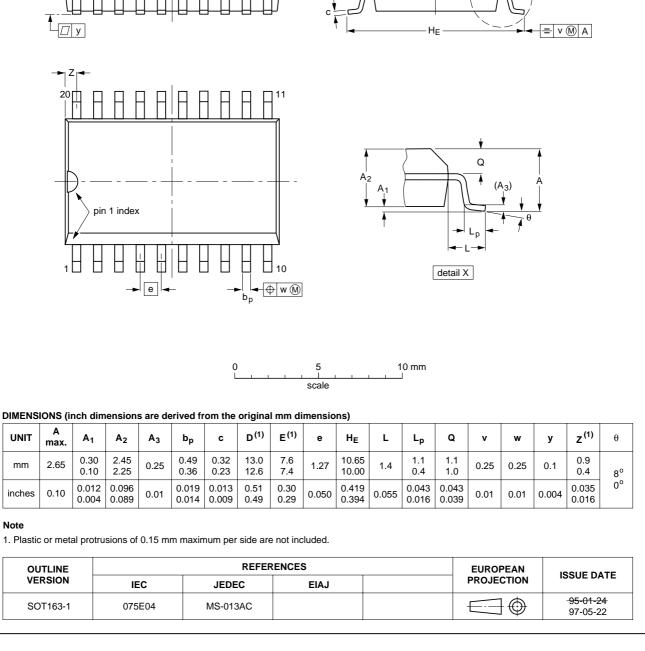
Double mixer/oscillator for TV and VCR tuners

PACKAGE OUTLINE

Philips Semiconductors

SO20: plastic small outline package; 20 leads; body width 7.5 mm

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SOT163-1

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonally- opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
more of the limiting values of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or may cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification limiting values for extended periods may affect device reliability.
Application information	
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Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.